

Crib sheet 3: (MOS devices, Schottky junctions, CMOS)

Electrostatic potentials for MOS capacitors

$$\phi(x) = \frac{1}{q} [E_i(\text{bulk}) - E_i(x)] \quad \phi_S = \frac{1}{q} [E_i(\text{bulk}) - E_i(\text{surface})]$$

Potential at position x

Potential at semiconductor/oxide interface

$$\phi_F = \frac{1}{q} [E_i(\text{bulk}) - E_F]$$

Bulk potential in semiconductor (ϕ_F depends on doping concentration)

Gate-Voltage relationship

$$V_G = \phi_S \pm \frac{\epsilon_{Si}}{\epsilon_{ox}} x_{ox} \sqrt{\frac{2qN_{A/D}}{\epsilon_{Si}} |\phi_S|} \quad +/- \text{ and } N_A/N_D \text{ for NMOS/PMOS}$$

Threshold voltage $V_G = V_T'$ if $\phi_S = 2\phi_F$ (V_T' doping dependent, see ϕ_F above)

Depletion layer width:
$$W = \sqrt{\frac{2\epsilon_{Si} |\phi_S|}{qN_{A/D}}} \quad (W = W_T \text{ if } \phi_S = 2\phi_F)$$

MOS-Capacitances:
$$C_{ox} = \frac{\epsilon_{ox}}{x_{ox}}; \quad C_S = \frac{\epsilon_{Si}}{W}; \quad C_G = \frac{C_S C_{ox}}{C_S + C_{ox}}$$

I-V relationships for NMOS devices: $Z =$ gate width, $L =$ gate length, $A =$ gate area $= Z \times L$

$$I_{DSat} = \frac{Z\mu C_{ox}}{2L} (V_G - V_T)^2 \text{ for } V_D > V_{DSat} \text{ and } V_G \geq V_T \text{ with } V_{DSat} = V_G - V_T$$

$$I_D = \frac{Z\mu C_{ox}}{L} \left[(V_G - V_T)V_D - \frac{V_D^2}{2} \right] \text{ for } 0 \leq V_D \leq V_{DSat} \text{ and } V_G \geq V_T$$

Small-signal parameters and cut-off frequency:

Below pinch-off: ($V_D \leq V_{DSat}$)
$$g_d = \frac{Z\mu C_{ox}}{L} (V_G - V_T - V_D) \quad g_m = \frac{Z\mu C_{ox}}{L} V_D$$

Under saturation: ($V_D > V_{DSat}$)
$$g_d = 0 \quad g_m = \frac{Z\mu C_{ox}}{L} (V_G - V_T)$$

cut-off frequency:
$$f_t = \frac{g_m}{2\pi C_G} \approx \frac{g_m}{2\pi C_{ox} A}$$

Relationships for real MOS devices:

Flatband voltage $V_{FB} = \frac{1}{q} \Phi_{MS} + \left(-\frac{Q_i}{C_{ox}}\right)$ with $\Phi_{MS} = \Phi_M - \Phi_S$

Real threshold voltage: $V_T = V_{FB} + V_T'$ (V_T' = threshold voltage of ideal device)

Relationships for MS (Schottky) junctions (n-type semiconductor):

Schottky barrier height: $\Phi_B = \Phi_M - \chi$ (independent of applied voltage)

Schottky-diode built-in potential: $qV_{bi} = \Phi_B - (E_c - E_F) = \Phi_B - \left[\frac{E_G}{2} - (E_F - E_i)\right]$

Ion implantation

Ion implantation profile: $N(x) = \frac{iondose}{\sqrt{2\pi\Delta R_p}} \exp\left[-\frac{1}{2}\left(\frac{x - R_p}{\Delta R_p}\right)^2\right]$ [*iondose*] = # of ions/cm²

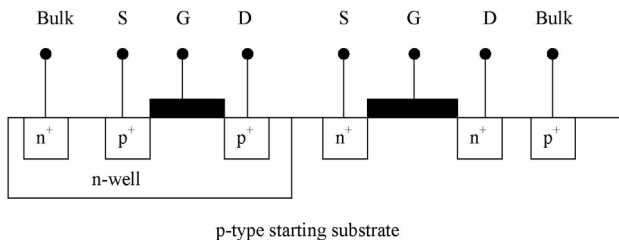
V_T -shift by ion-implantation: $|\Delta V_T| = \left|\frac{q \text{ iondose}}{C_{ox}}\right|$

Boron ions in Si → acceptors: $\Delta V_T > 0$ (positive shift)

Phosphorous ions in Si → donors: $\Delta V_T < 0$ (negative shift)

CMOS schematic for p-type starting substrate

(for n-type starting substrate change conductivity types appropriately)



PFET

NFET